

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application. The following listing provides the amended claims with the amendments marked with deleted material in crossed out and new material underlined to show the changes made.

5 **Listing of Claims:**

1. (Original) An integrated circuit ("IC") layout comprising a first set of vias that have a diamond shape and a second set of vias that have a rectangular shape.

2. (Currently Amended) The IC layout of claim 1, wherein a first via in the first set traverses two layers of the IC layout and the first via has a contact on each of the layers, wherein
10 each contact is in the shape of a diamond.

3. (Currently Amended) The IC layout of claim 2, wherein a second via in the second set traverses two layers of the IC layout and the second via has a contact on each of the layers, wherein each contact of the second via is in the shape of a rectangle.

4. (Currently Amended) An integrated-circuit ("IC") layout comprising:
15 _____ a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein one of the contacts is in the shape of a rectangle and one of the contacts is in the shape of a diamond;

_____ a first set of interconnect lines terminating on at least a plurality of the first set of vias, wherein the interconnect lines in the first set of interconnect lines have ends that
20 terminate on said contacts, wherein a plurality of the interconnect line ends are in shape of a half polygon, wherein the polygon has more than four sides.

5. (Original) The IC layout of claim 4, wherein the rectangle is a square.

6. (Currently Amended) The IC layout of claim 4, wherein the rectangle has a different length and width.

7. (Original) The IC layout of claim 4, wherein the diamond has four equal
5 sides.

8. (Original) The IC layout of claim 4, wherein the diamond has two pairs of sides, wherein the length of one pair of sides is different than the length of the other pair of sides.

9. (Currently Amended) An integrated-circuit ("IC") layout comprising a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of
10 the layers, wherein one of the contacts is in the shape of a quadrilateral polygon and one of the contacts is in the shape of a non-quadrilateral polygon.

10. (New) The IC layout of claim 4, wherein the interconnect line ends are in the shape of a half-octagon.

11. (New) The IC layout of claim 4, wherein the interconnect line ends are in
15 the shape of a half-hexagon.

12. (New) The IC layout of claim 4, wherein the interconnect lines with half polygonal ends terminate on the diamond shaped contacts.